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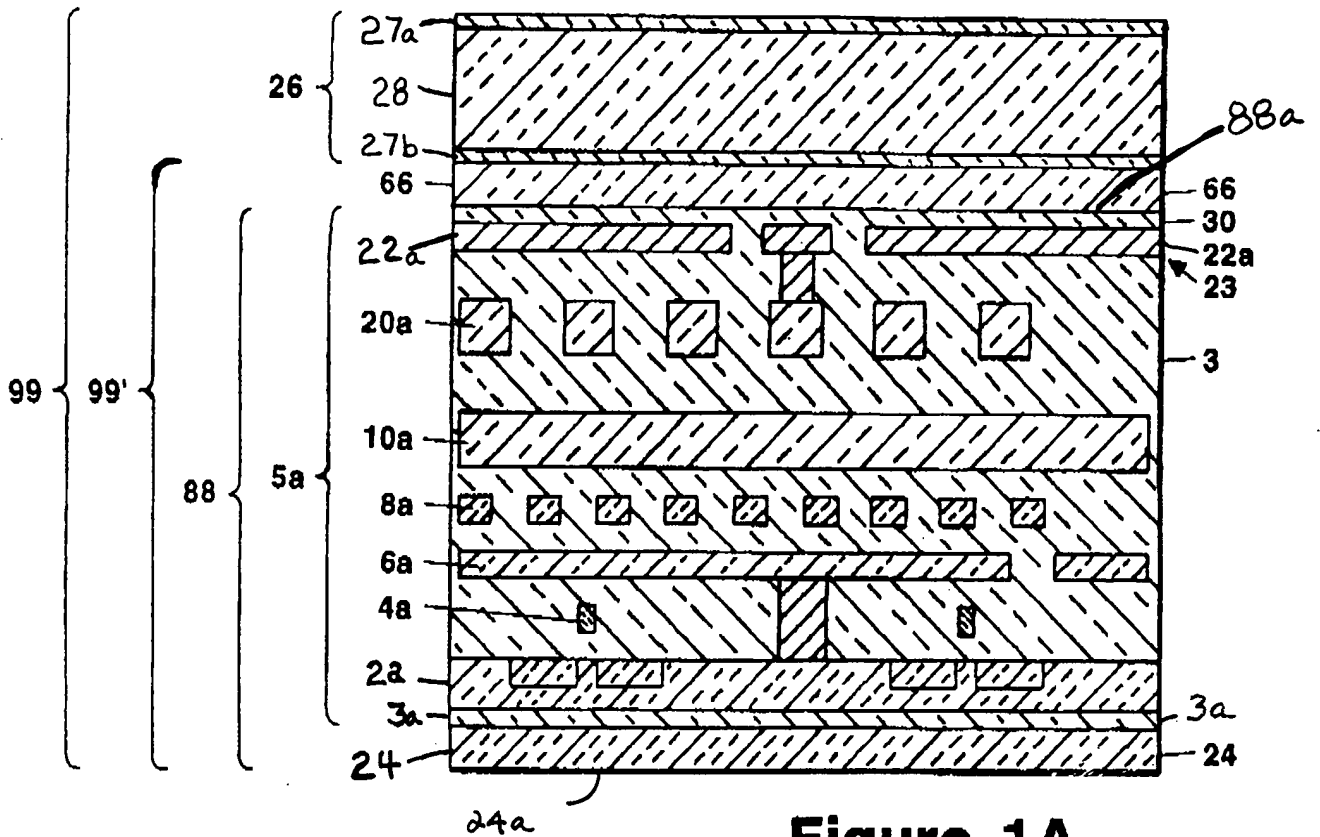


Figure 1A

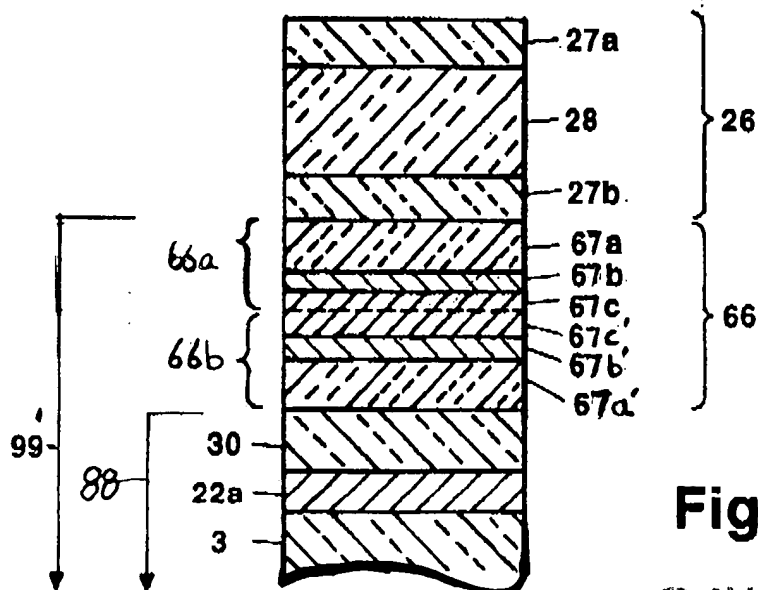


Figure 1B

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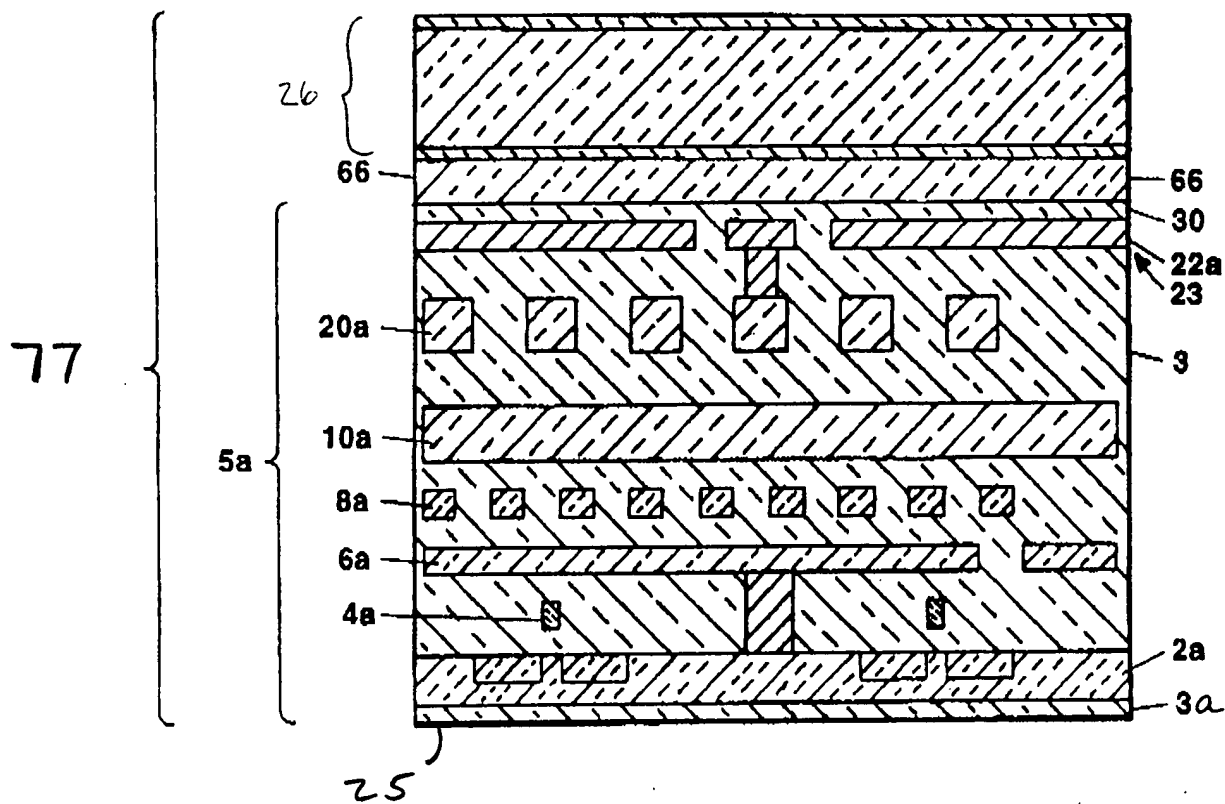


Figure 2A



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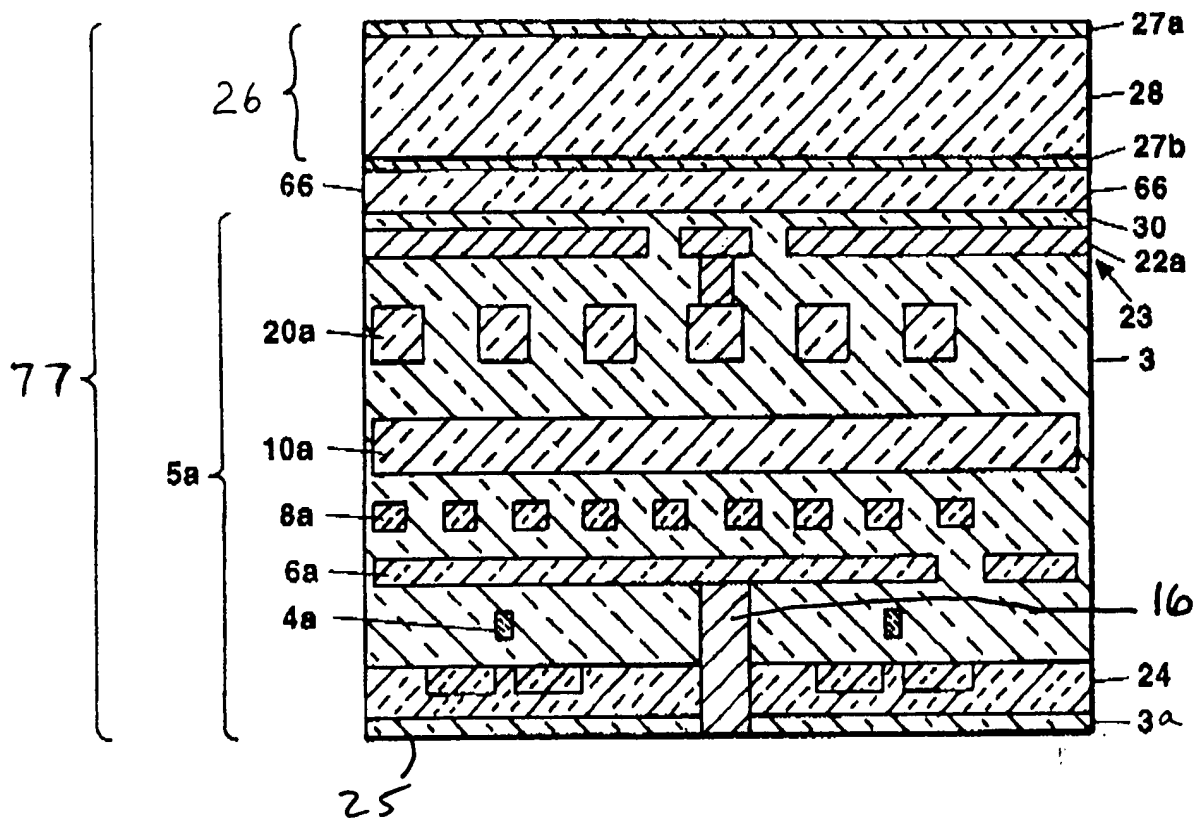
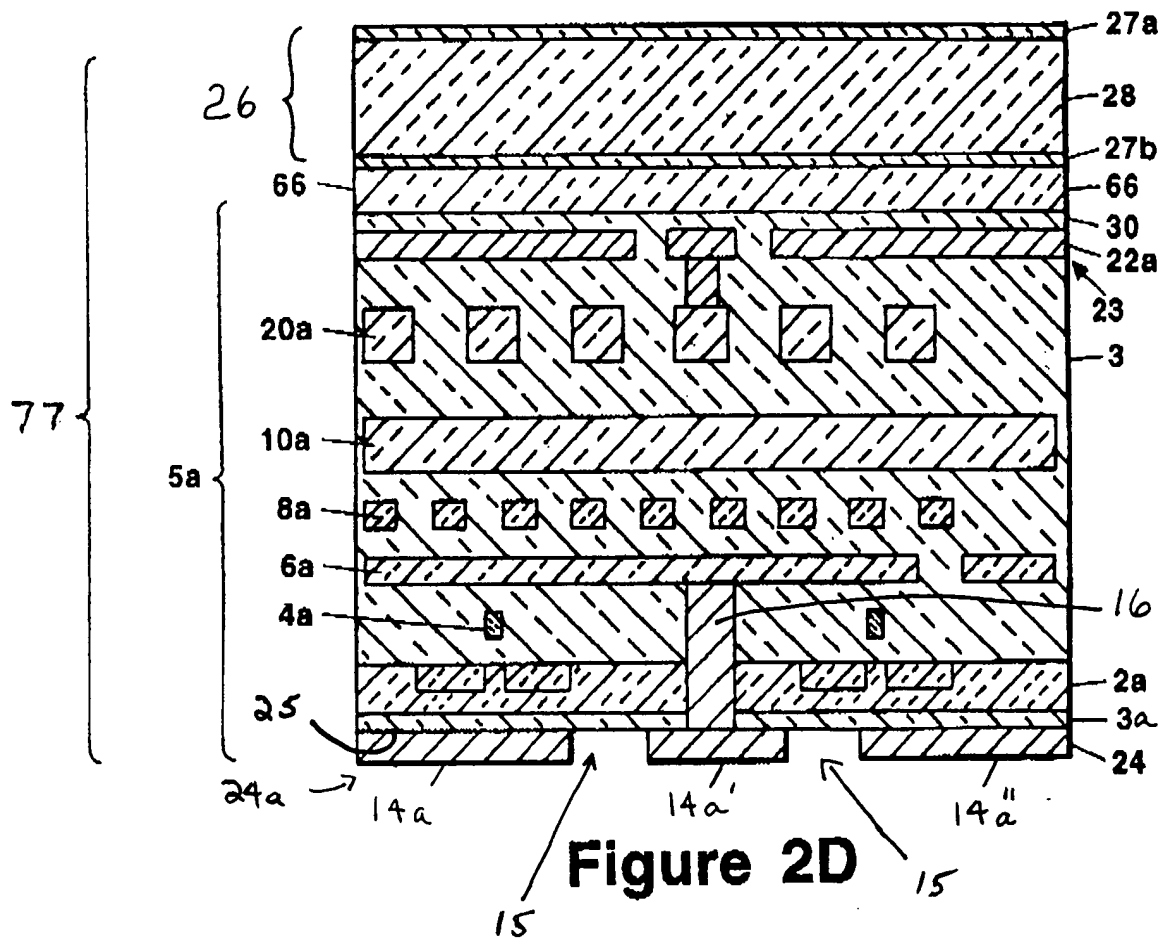


Figure 2C

METHOD OF FORMING A MULTI-LAYER SEMICONDUCTOR STRUCTURE INCORPORATING
A PROCESSING HANDLE MEMBER

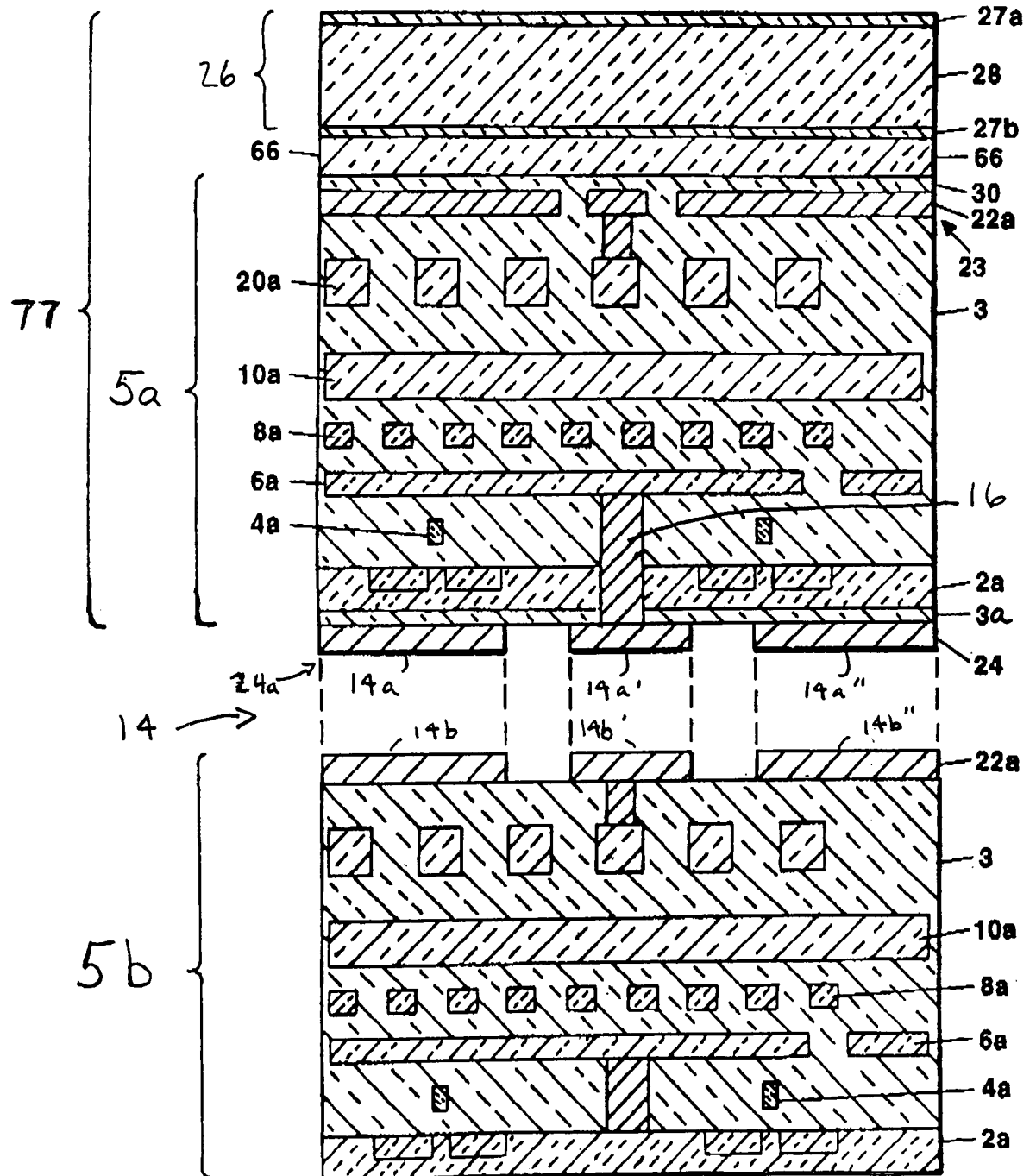
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Figure 3A

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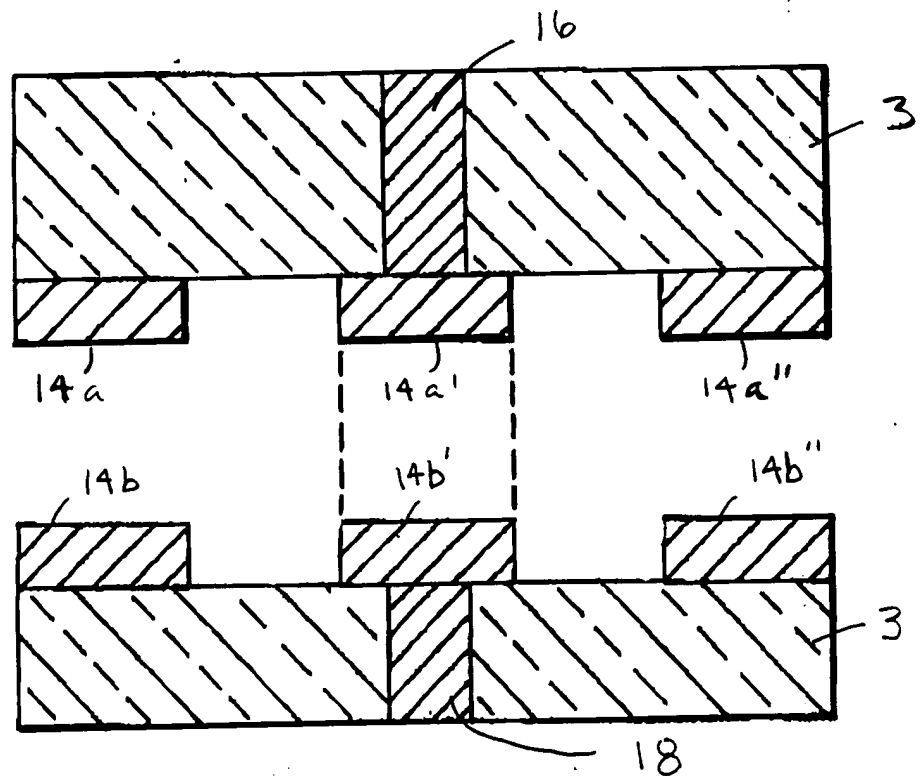


Figure 3B

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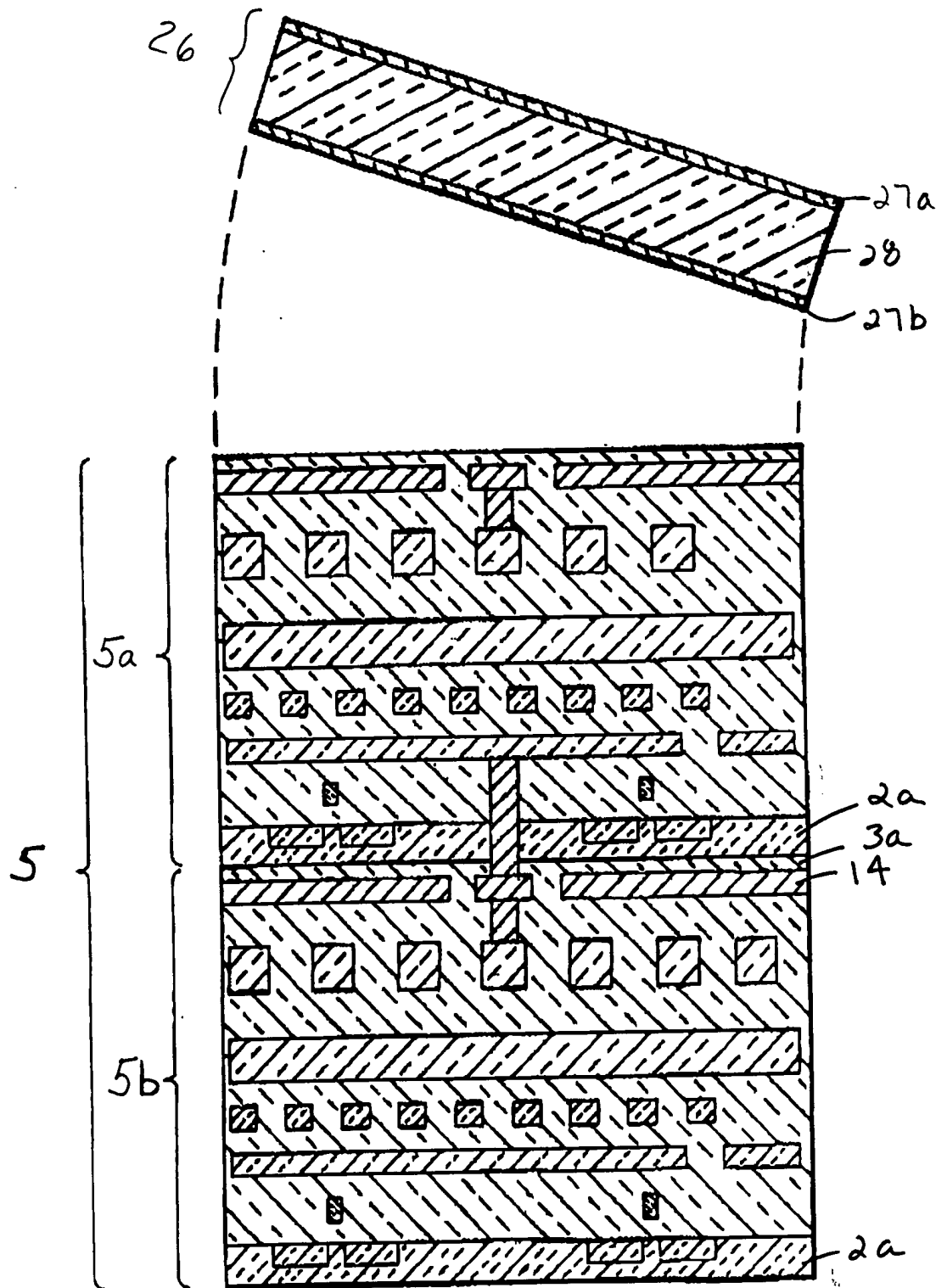


Figure 4A

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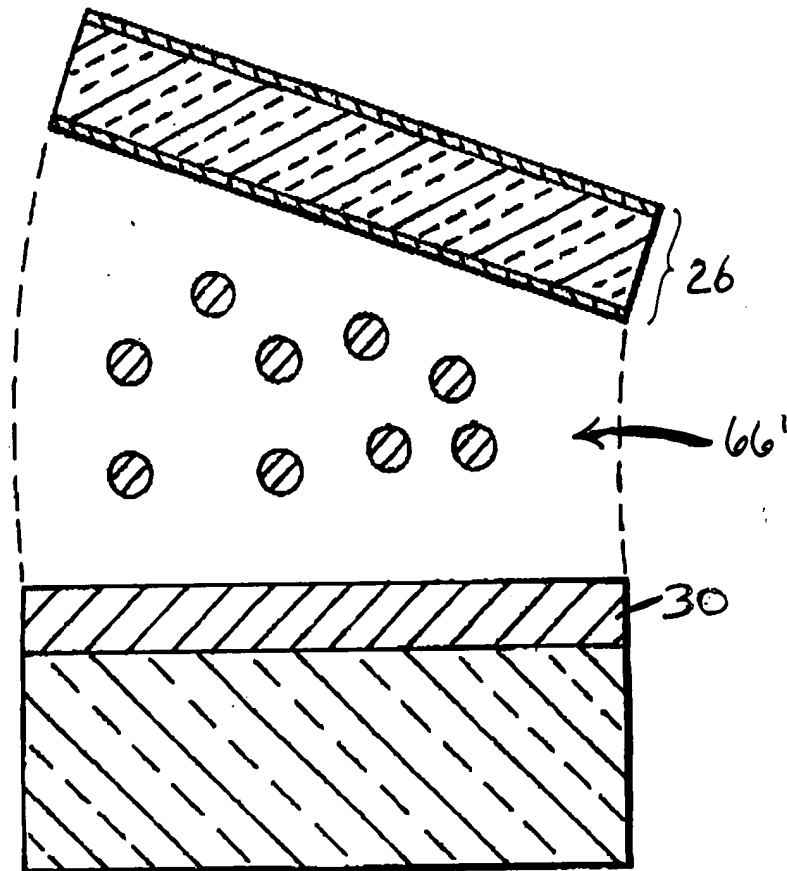


Figure 4B